



Material Content Data Sheet



Sales Product Name		SP370-25-116-0		Issued		25. September 2017			
MA#		MA000979034							
Package		PG-DSOSP-14-64		Weight*		610.02 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	12.623	2.07	2.07	20693	20693	
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		72		
		non noble metal	zinc	7440-66-6	0.176	0.03		288	
		non noble metal	iron	7439-89-6	3.511	0.58		5756	
wire	noble metal	non noble metal	copper	7440-50-8	142.572	23.37	23.99	233716	239832
		noble metal	gold	7440-57-5	0.941	0.15	0.15	1542	1542
		organic material	carbon black	1333-86-4	0.878	0.14		1439	
encapsulation	plastics	epoxy resin	-	47.409	7.77		77717		
		inorganic material	silicondioxide	60676-86-0	390.684	64.05	71.96	640445	719601
leadfinish	non noble metal	tin	7440-31-5	4.526	0.74	0.74	7419	7419	
plating	noble metal	silver	7440-22-4	2.637	0.43	0.43	4322	4322	
glue	plastics	maleimide resin	-	0.804	0.13		1318		
		noble metal	silver	7440-22-4	3.217	0.53	0.66	5273	6591
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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